

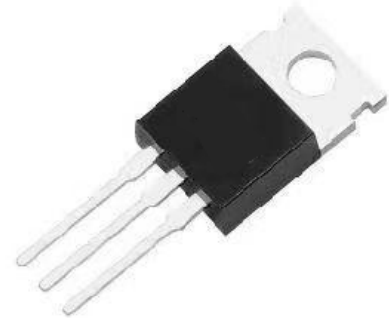
TPGP15N65LN

IGBT Discrete with Anti-Parallel Diode

General Description

Topdiode TPGP15N65LN 15A 650V IGBT Discrete provides ultra-low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

Package TO-220-3



Features

High Breakdown Voltage up to 650V for Improved Reliability

Trench Field Stop Technology

High Ruggedness, Temperature Stable

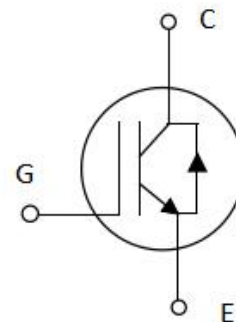
Low switching losses

Easy Parallel Switching Capability due to Positive

Temperature Coefficient in V_{CEsat}

Maximum junction temperature 175°C

Equivalent Schematic



Applications

Uninterruptible Power Supply

Inverter

Converter with High Switching Frequency

Summary

Symbol	Value
V_{CE}	650V
I_C	15A
$V_{CE(SAT)} I_C=15A$	1.65V

Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Description	Value	Unit	
V_{CE}	Collector-Emitter Breakdown Voltage	650	V	
I_C	DC Collector Current, Limited by T_{jmax}	$T_C=25^\circ\text{C}$	30	A
		$T_C=100^\circ\text{C}$	15	A
I_F	Diode Forward Current, Limited by T_{jmax}	$T_C=25^\circ\text{C}$	30	A
		$T_C=100^\circ\text{C}$	15	A
V_{GE}	Continuous Gate-Emitter voltage	± 20	V	
V_{GE}	Transient Gate-Emitter voltage	± 30	V	
I_{CRM}	Repetitive peak collector current, $t_p = 1\text{ms}$	30	A	
I_{CM}	Pulse Collector Current, $V_{GE} = 15\text{V}$, t_p Limited by T_{jmax}	60	A	
T_{SC}	Short Circuit Withstand Time, $V_{GE} = 15\text{V}$, $V_{CE} \leq 400\text{V}$	5	us	
P_{tot}	Power Dissipation, $T_j = 25^\circ\text{C}$	130	W	
T_j	Operating Junction Temperature	-40 to +175	$^\circ\text{C}$	
T_s	Storage Temperature	-55 to +150	$^\circ\text{C}$	
-	Soldering Temperature, Wave Soldering 1.6mm (0.063in.) from Case for 10s	260	$^\circ\text{C}$	

Thermal Characteristics

Symbol	Description	Max	Unit
R_{thJC}	IGBT Thermal Resistance, Junction - Case	1.15	K/W
R_{thJC}	Diode Thermal Resistance, Junction - Case	1.9	K/W
R_{thJA}	Thermal Resistance, Junction - Ambient	60	K/W

Electrical Characteristics (T_j= 25°C unless otherwise specified)

Symbol	Description	Conditions	Min	Typ	Max	Unit
Static						
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} =0V, I _C =250uA	650			V
		V _{GE} =0V, I _C =1mA	650			V
V _{GE(th)}	Gate Threshold Voltage	V _{GE} =V _{CE} , I _C =250uA	4.1	5.0	5.7	V
V _(sat)	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C =10A	T _j =25°C	1.65		V
			T _j =125°C	1.95		
			T _j =150°C	2.05		
I _{CES}	Zero Gate Voltage Collector Current	V _{CE} = 650V, V _{GE} = 0V	T _j =25°C		250	μA
			T _j =150°C		250	
I _{GES}	Gate-Emitter Leakage Current	V _{CE} = 0V, V _{GE} = ±20V			200	nA
Dynamic						
C _{ies}	Input Capacitance	V _{CE} =25V, V _{GE} = 0V, f=1MHz		0.99		nF
C _{res}	Reverse Transfer Capacitance			0.03		
Q _G	Gate Charge	V _{CC} = 480V, I _C = 15A, V _{GE} = 15V		52		nC
I _{SC}	Short Circuit Collector Current	V _{CC} = 400V, t _{sc} ≤ 5us, V _{GE} = 15V, T _{j,start} =25° C		98		A

Switching Characteristic, Inductive Load

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Unit
Dynamic T_j=25°C						
t _{d(on)}	Turn-on Delay Time	V _{CC} =400V, I _C =15.0A, V _{GE} =0.0/15.0V, R _g =12Ω		15		ns
t _r	Rise Time			25		ns
t _{d(off)}	Turn-off Delay Time			60		ns
t _f	Fall Time			46		ns
E _{on}	Turn-on Energy			0.75		mJ
E _{off}	Turn-off Energy			0.1		mJ
Dynamic T_j=125°C						
t _{d(on)}	Turn-on Delay Time	V _{CC} =400V, I _C =15.0A,		24		ns

t_r	Rise Time	$V_{GE}=0.0/15.0V,$ $R_g=12\Omega$		30		ns
$t_{d(off)}$	Turn-off Delay Time			90		ns
t_f	Fall Time			54		ns
E_{on}	Turn-on Energy			1.10		mJ
E_{off}	Turn-off Energy			0.15		mJ

Dynamic $T_j=150^\circ C$

$t_{d(on)}$	Turn-on Delay Time	$V_{CC} =400V, I_C=15.0A,$ $V_{GE}=0.0/15.0V,$ $R_g=12\Omega$		26		ns
t_r	Rise Time			32		ns
$t_{d(off)}$	Turn-off Delay Time			95		ns
t_f	Fall Time			58		ns
E_{on}	Turn-on Energy			1.25		mJ
E_{off}	Turn-off Energy			0.18		mJ

Electrical Characteristics of the DIODE ($T_j = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Unit
V_{FM}	Diode Forward Voltage	$I_F = 15A, T_j=25^\circ C$		1.7		V
		$I_F = 15A, T_j=125^\circ C$		1.65		
		$I_F = 15A, T_j=150^\circ C$		1.65		
I_{rr}	Reverse Recovery Current	$I_F= 15A,$ $V_R = 400V,$ $di/dt= -150A/\mu s,$ $T_j=25^\circ C$		12		A
Q_{rr}	Reverse Recovery Charge			0.5		μC
E_{rec}	Reverse Recovery Energy			0.06		mj
I_{rr}	Reverse Recovery Current	$I_F= 15A,$ $V_R = 400V,$ $di/dt= -150A/\mu s,$ $T_j=125^\circ C$		15		A
Q_{rr}	Reverse Recovery Charge			0.9		μC
E_{rec}	Reverse Recovery Energy			0.12		mj
I_{rr}	Reverse Recovery Current	$I_F= 15A,$ $V_R = 400V,$ $di/dt= -150A/\mu s,$ $T_j=150^\circ C$		16		A
Q_{rr}	Reverse Recovery Charge			1.2		μC
E_{rec}	Reverse Recovery Energy			0.15		mj

Typical Performance

Fig. 1 FBSOA characteristics

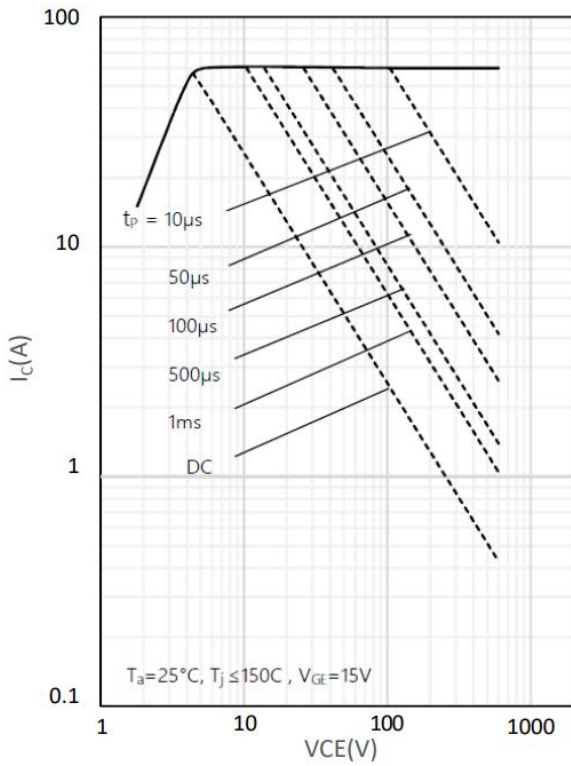


Fig. 2 Load Current vs. Frequency

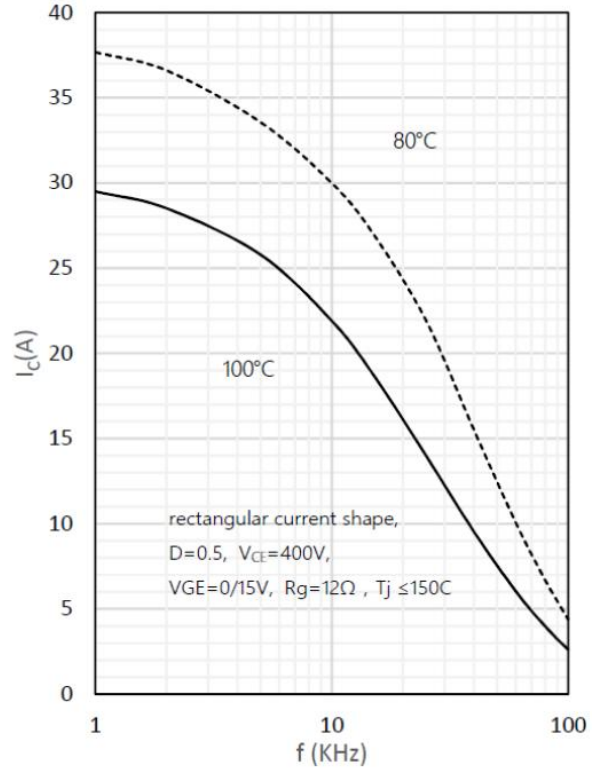


Fig. 3 Output characteristics

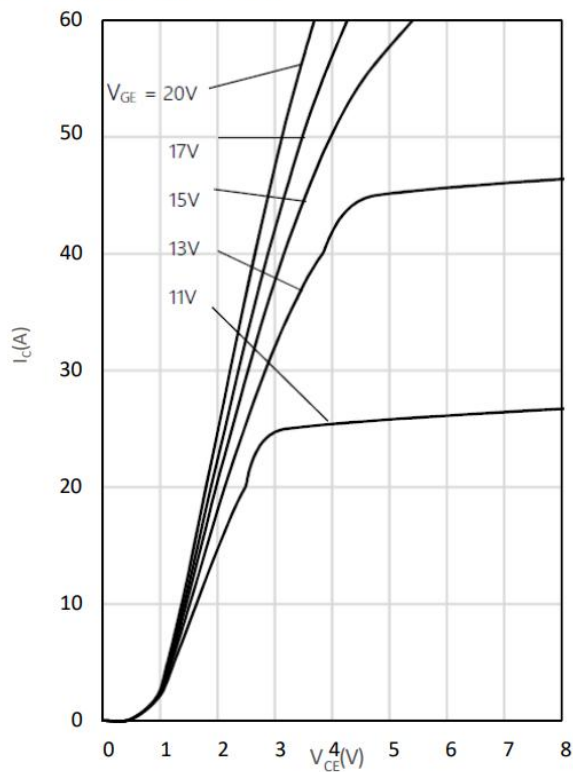
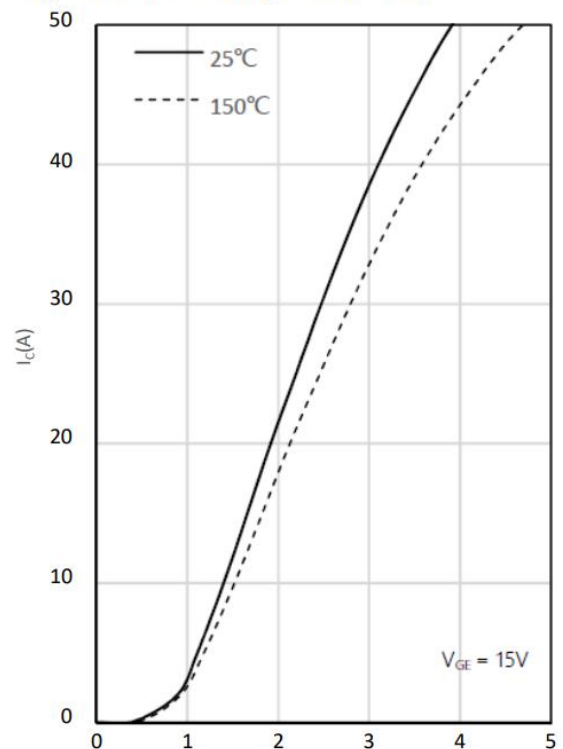


Fig. 4 Saturation voltage characteristics



Typical Performance

Fig. 5 Switching times vs. gate resistor

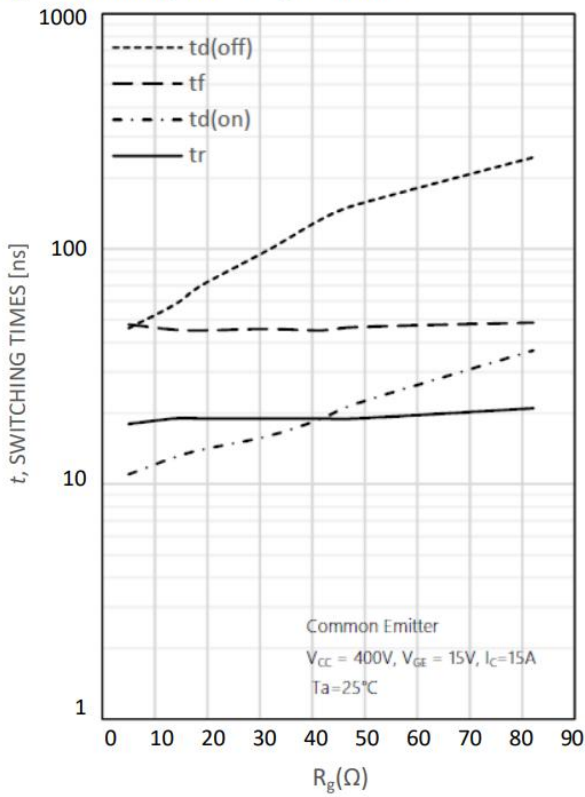


Fig. 6 Switching times vs. collector current

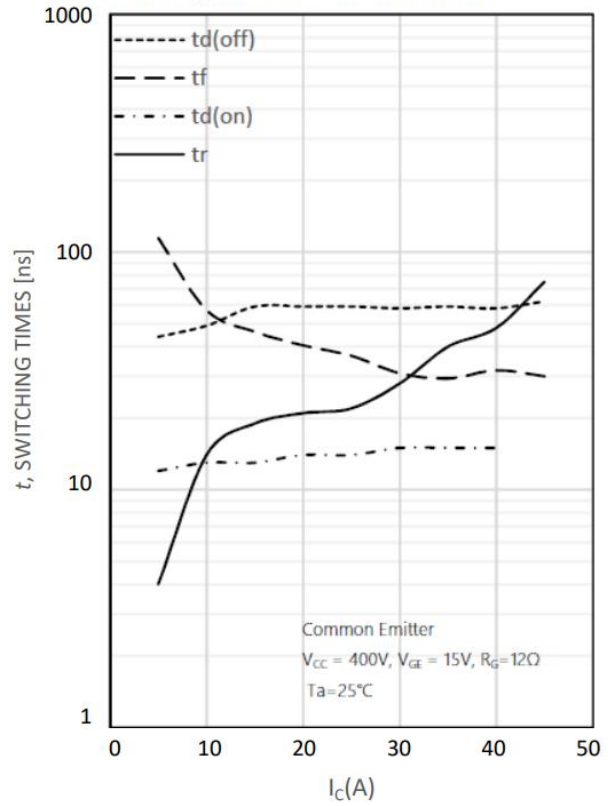


Fig. 7 Switching loss vs. gate resistor

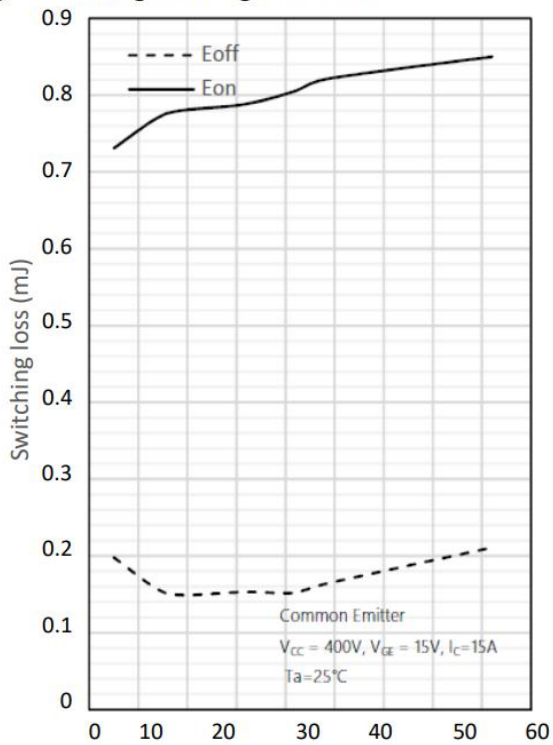
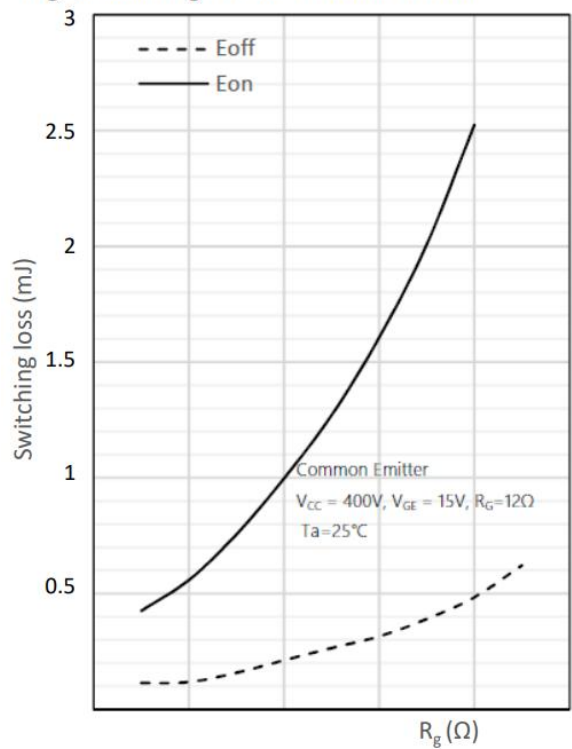


Fig. 8 Switching loss vs. collector current



Typical Performance

Fig. 9 Gate charge characteristics

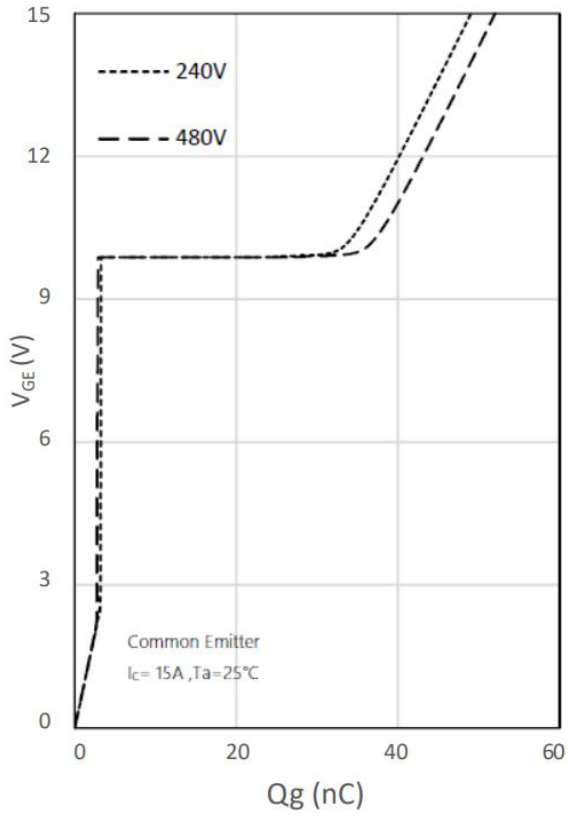
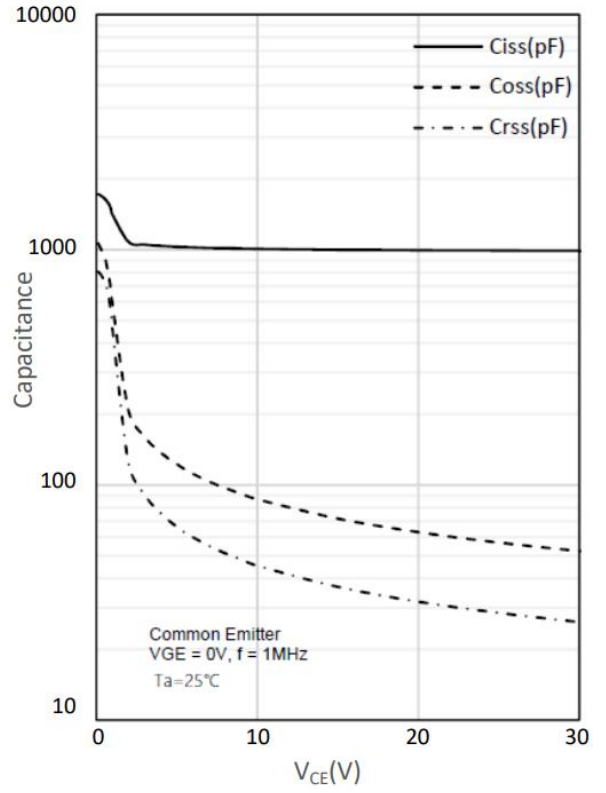
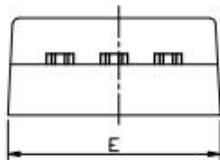
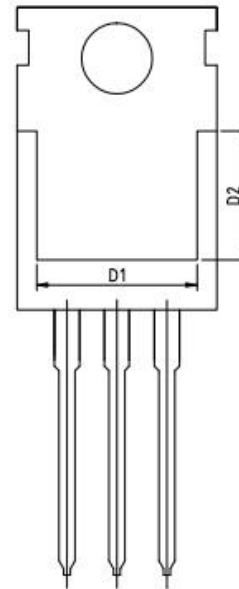
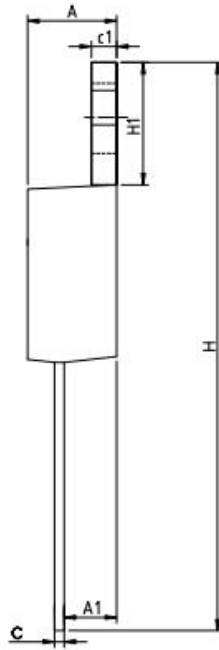
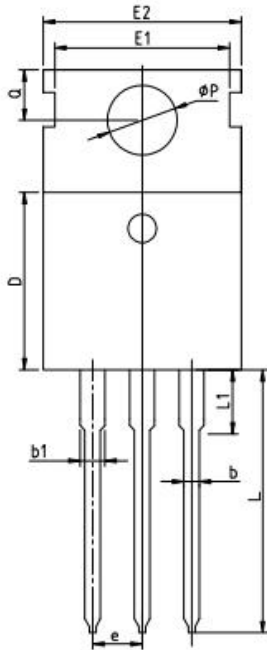


Fig. 10 Capacitance characteristics

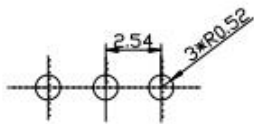


Package Dimensions

TO-220CB-3L



RECOMMENDED LAND PATTERN



	MIN	NOM	MAX
A	4.40	4.60	4.80
A1	2.25	2.40	2.55
b	0.72	0.82	0.92
b1	1.12	1.27	1.42
c	0.40	0.50	0.60
c1	1.20	1.30	1.40
D	8.80	9.10	9.40
D1	7.75	7.95	8.15
D2	6.55	6.75	6.95
e		2.54BSC	
E	9.65	10.00	10.35
E1		8.70	
E2	9.70	10.00	10.30
H	28.70	29.20	29.70
H1	6.25	6.50	6.85
L	13.20	13.50	13.80
L1	2.80	3.10	3.40
Q	2.60	2.80	3.00
ØP	3.45	3.60	3.75

UNIT:mm